



**N - CHANNEL ENHANCEMENT MODE  
POWER MOS TRANSISTORS**

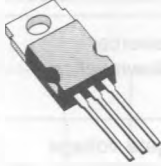
TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
SGSP361	100 V	0.15 Ω	18 A
SGSP362	80 V	0.1 Ω	22 A

- HIGH SPEED SWITCHING APPLICATIONS
- 80 - 100 VOLTS - FOR UPS APPLICATIONS
- ULTRA FAST SWITCHING
- RATED FOR UNCLAMPED INDUCTIVE SWITCHING (ENERGY TEST) ♦
- EASY DRIVE FOR REDUCED SIZE AND COST

**INDUSTRIAL APPLICATIONS:**


- UNINTERRUPTIBLE POWER SUPPLIES
- MOTOR CONTROLS

N - channel enhancement mode POWER MOS field effect transistor. Easy drive and very fast switching times make this POWER MOS transistor ideal for high speed switching applications. Typical applications include UPS, battery chargers, printer hammer drivers, solenoid drivers and motor control.



**TO-220**

**INTERNAL SCHEMATIC DIAGRAM**



**ABSOLUTE MAXIMUM RATINGS**

		SGSP361	SGSP362	
V <sub>DS</sub>	Drain-source voltage (V <sub>GS</sub> = 0)	100	80	V
V <sub>DGR</sub>	Drain-gate voltage (R <sub>GS</sub> = 20 KΩ)	100	80	V
V <sub>GS</sub>	Gate-source voltage		± 20	V
I <sub>D</sub>	Drain current (cont.) at T <sub>c</sub> = 25°C	18	22	A
I <sub>D</sub>	Drain current (cont.) at T <sub>c</sub> = 100°C	11	14	A
I <sub>DM</sub> (*)	Drain current (pulsed)	72	88	A
P <sub>tot</sub>	Total dissipation at T <sub>c</sub> < 25°C		100	W
	Derating factor		0.8	W/°C
T <sub>stg</sub>	Storage temperature		- 65 to 150	°C
T <sub>j</sub>	Max. operating junction temperature		150	°C

(\*) Pulse width limited by safe operating area  
♦ Introduced in 1988 week 44

**THERMAL DATA**

$R_{thj-case}$	Thermal resistance junction-case	max	1.25	°C/W
$T_L$	Maximum lead temperature for soldering purpose		275	°C

**ELECTRICAL CHARACTERISTICS** ( $T_{case} = 25^{\circ}\text{C}$  unless otherwise specified)

Parameters	Test Conditions	Min.	Typ.	Max.	Unit
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**OFF**

$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 250 \mu\text{A}$ for <b>SGSP361</b> for <b>SGSP362</b>	$V_{GS} = 0$	100 80		V V
$I_{DSS}$	Zero gate voltage drain current ( $V_{GS} = 0$ )	$V_{DS} = \text{Max Rating}$ $V_{DS} = \text{Max Rating} \times 0.8$	$T_c = 125^{\circ}\text{C}$		250 1000	$\mu\text{A}$ $\mu\text{A}$
$I_{GSS}$	Gate-body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 20 \text{ V}$			$\pm 100$	nA

**ON (\*)**

$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$	$I_D = 250 \mu\text{A}$	2		4	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10 \text{ V}$ $I_D = 9 \text{ A}$ for <b>SGSP361</b> $I_D = 11 \text{ A}$ for <b>SGSP362</b> $V_{GS} = 10 \text{ V}$ $I_D = 9 \text{ A}$ for <b>SGSP361</b> $I_D = 11 \text{ A}$ for <b>SGSP362</b>	$T_c = 100^{\circ}\text{C}$			0.15 0.1 0.3 0.2	$\Omega$ $\Omega$ $\Omega$ $\Omega$

**ENERGY TEST**

$I_{UIS}$	Unclamped inductive switching current (single pulse)	$V_{DD} = 30 \text{ V}$ starting $T_j = 25^{\circ}\text{C}$ for <b>SGSP361</b> for <b>SGSP362</b>	$L = 100 \mu\text{H}$	18 22			A A
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**DYNAMIC**

$g_{fs}$	Forward transconductance	$V_{DS} = 25 \text{ V}$	$I_D = 9 \text{ A}$	4.5			mho
$C_{iss}$	Input capacitance				950	1200	pF
$C_{oss}$	Output capacitance	$V_{DS} = 25 \text{ V}$	$f = 1 \text{ MHz}$			480	pF
$C_{rss}$	Reverse transfer capacitance	$V_{GS} = 0$				230	pF

## ELECTRICAL CHARACTERISTICS (Continued)

Parameters	Test Conditions	Min.	Typ.	Max.	Unit
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## SWITCHING

$t_{d(on)}$	Turn-on time	$V_{DD} = 50\text{ V}$	$I_D = 11\text{ A}$	20	30	ns
$t_r$	Rise time	$V_i = 10\text{ V}$	$R_i = 4.7\ \Omega$	50	65	ns
$t_{d(off)}$	Turn-off delay time	(see test circuit)		65	85	ns
$t_f$	Fall time			25	35	ns

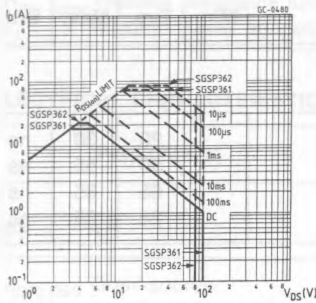
## SOURCE DRAIN DIODE

$I_{SD}$	Source-drain current	for <b>SGSP361</b> for <b>SGSP362</b>			18 22	A A
$I_{SDM}$ (*)	Source-drain current (pulsed)	for <b>SGSP361</b> for <b>SGSP362</b>			72 88	A A
$V_{SD}$	Forward on voltage	$V_{GS} = 0$ $I_{SD} = 18\text{ A}$ for <b>SGSP361</b> $I_{SD} = 22\text{ A}$ for <b>SGSP362</b>			1.35 1.35	V V
$t_{rr}$	Reverse recovery time	$I_{SD} = 22\text{ A}$ $di/dt = 25\text{ A}/\mu\text{s}$	$V_{GS} = 0$	180		ns

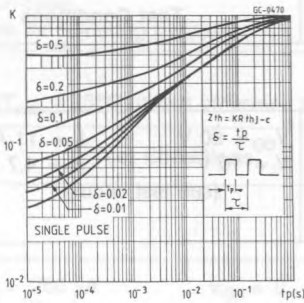
(\*) Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

(\*) Pulse width limited by safe operating area

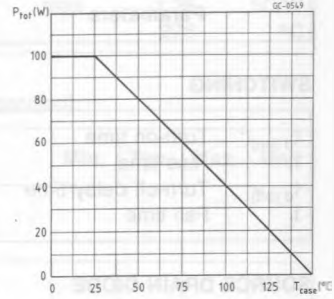
Safe operating areas



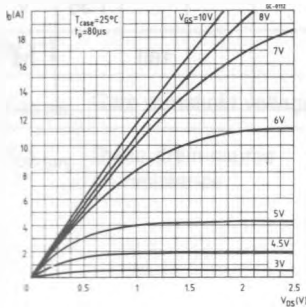
Thermal impedance



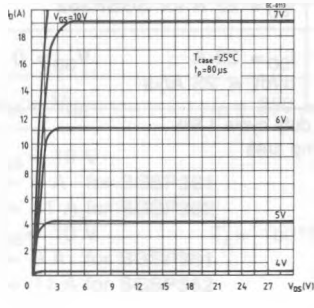
Derating curve



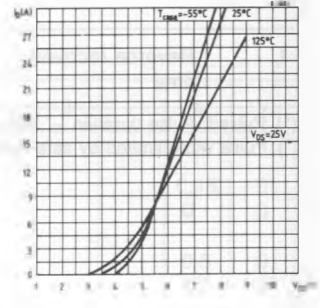
Output characteristics



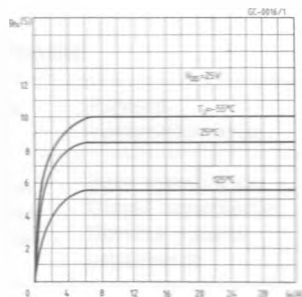
Output characteristics



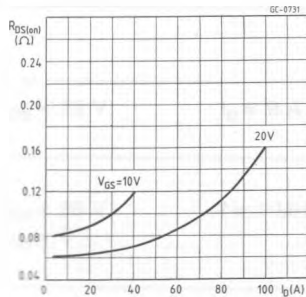
Transfer characteristics



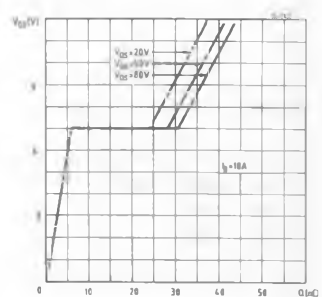
Transconductance



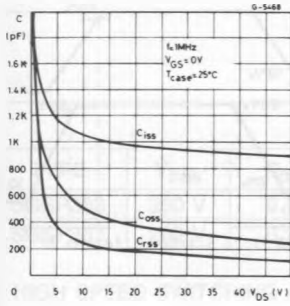
Static drain-source on resistance



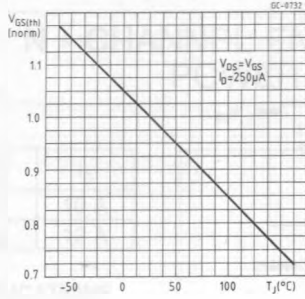
Gate charge vs gate-source voltage



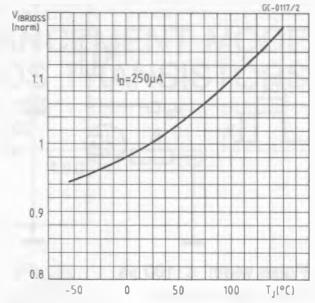
Capacitance variation



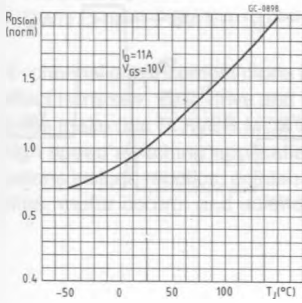
Normalized gate threshold voltage vs temperature



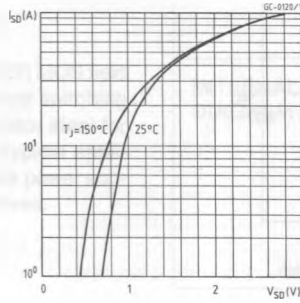
Normalized breakdown voltage vs temperature



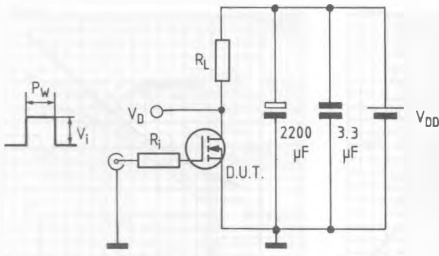
Normalized on resistance vs temperature



Source-drain diode forward characteristics



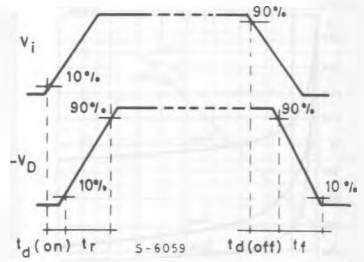
Switching times test circuit for resistive load



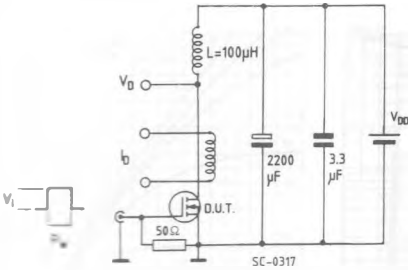
Pulse width  $\leq 100 \mu\text{s}$   
 Duty cycle  $\leq 2\%$

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Switching time waveforms for resistive load



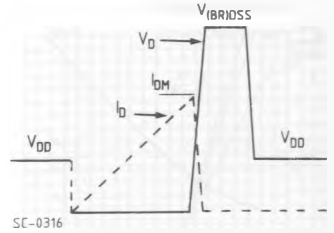
Unclamped inductive load test circuit



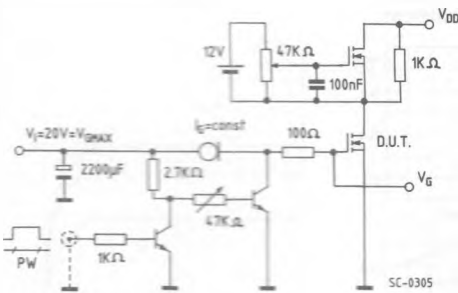
$V_i = 12 \text{ V}$  - Pulse width: adjusted to obtain specified  $I_{DM}$

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Unclamped inductive waveforms



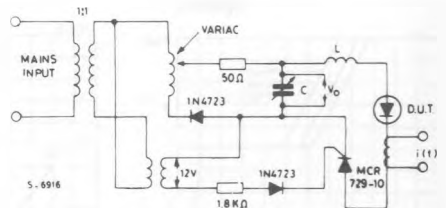
Gate charge test circuit



PW adjusted to obtain required  $V_G$

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Body-drain diode  $t_{rr}$  measurement  
 Jedec test circuit



S. 6916